

Multi Line AOI for THT

AOI system for THT assemblies

- inspection of THT components, THT solder joints and SMT components
- double-sided inspection of THT PCBAs in the upper or lower transport module, with or without carrier
- fully automatic AOI test program generation with MagicClick in a few minutes
- flexible data interfaces for line communication and for MES and traceability



Technical specifications

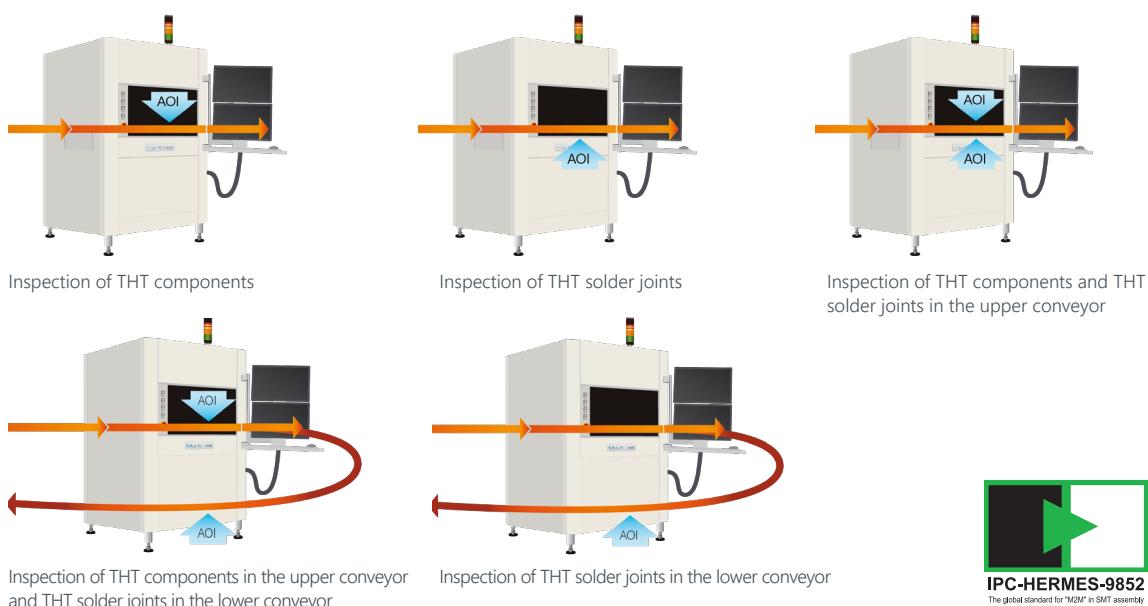
Camera modules

	2D AOI module	2D AOI module with angled view	3D AOI module
image capturing	orthogonal camera module with telecentric optics	orthogonal camera module with telecentric optics and 4 or 8 oblique view camera modules	3D/2D camera module with orthogonal camera, telecentric optics and 3D image capturing sensors
resolution per pixel	25 µm	25 µm (orthogonal) 35 µm (angled view)	15 µm
max. inspection height	up to 50 mm	up to 50 mm	35 mm
component clearance	up to 140 mm	up to 140 mm	40 mm (optionally 50 mm or 60 mm)
can be used in Multi line	component inspection from above	component inspection from above	solder joint and component inspection from above and below

Multi Line platform

max. inspection area	540 mm x 450 mm
max. carrier size	up to 620 mm x 510 mm
max. transport weight	15 kg
energy requirement	230 VAC / 2 kVA, compressed air 6 bar, consumption < 20 l/h
transport system	conveyor belt for PCBAs with or without carriers
transport direction	left-right, right-left, left-left, right-right
inline interface	SMEMA, HERMES, Siemens, Sensor
dimensions (w x d x h)	1150 mm x 1300 mm x 1800 mm
weight	approx. 800 kg

Configuration variants



ISO 9001 certified

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